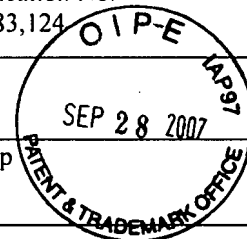


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U.S. Department of Commerce  
Patent and Trademark OfficeAtty. Docket No.  
P29662Application No.  
10/583,124INFORMATION DISCLOSURE STATEMENT  
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Bernd SZYSKA et al.Filing Date  
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## U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	4 8 6 6 0 3 2	09/12/89	FUJIMORI et al.			
	5 5 5 8 7 5 0	09/24/96	SZCZYRBOWSKI			
	5 3 8 4 0 2 1	01/24/95	THWAITES			

## FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
0 2 9 1 0 4 4	11/17/88	E.P.O.			
4 4 1 8 9 0 6	12/07/95	GERMANY			
0 5 3 7 0 1 1	04/14/93	E.P.O.			
1 2 3 2 2 9 3	08/21/02	E.P.O.			
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EXAMINER

DATE CONSIDERED

\*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.